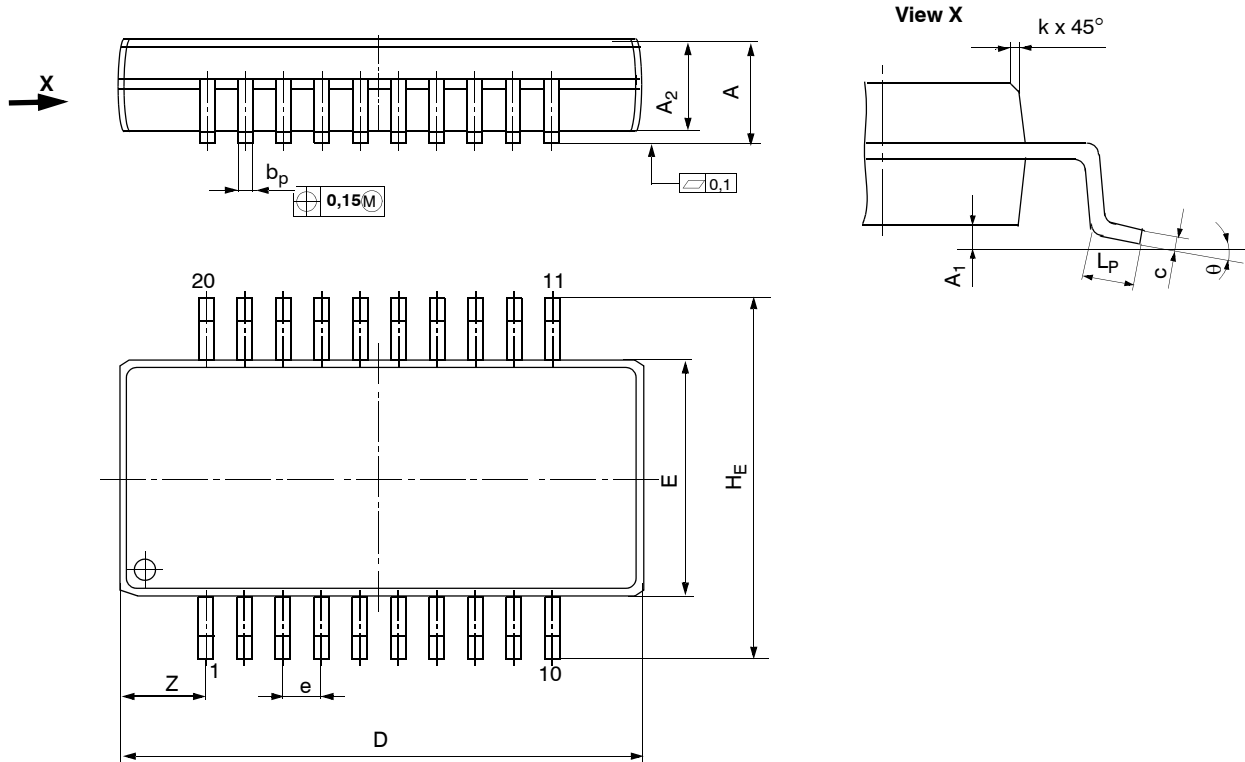
	Package SSOP20 (3,9 mm)	MDS 767
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Dimensions in millimetres

Based on JEDEC JEP95: MO-137

1 Dimensions

Dimensions of Sub-Group B1	
A_{max}	1,73
b_{Pmin}	0,20
b_{Pmax}	0,30
e_{nom}	0,635
H_{Emin}	5,84
H_{Emax}	6,20
L_{Pmin}	0,41
Z_{max}	1,5

Dimensions of Sub-Group C1	
A_{min}	1,54
A_{1min}	0,10
A_{1max}	0,25
A_{2min}	1,40
A_{2max}	1,55
c_{min}	0,18
c_{max}	0,25
D_{min}^*	8,55
D_{max}^*	8,73
E_{min}^*	3,82
E_{max}^*	4,00
k_{min}	0,25
θ_{min}	0°
θ_{max}	10°

- 2 Weight** ≤ 0,4 g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

* without mold-flash

Zentrum Mikroelektronik Dresden		
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